



Learning by Sharing

Shen-Li FU*

The IMPACT-EMAP 2014 (9th International Microsystems, Packaging, Assembly and Circuits Technology and 16th International Conference on Electronic Materials and Packaging) has been ended successfully in Nangang Exhibition Center, Taipei, on October 24, 2014. As the general chair of the conference, I sincerely appreciate the contributions and participations of all the authors, speakers and attendees. I would also like to cordially acknowledge the efforts of all the committee members, staffs and the session chairs. Without their participation and contribution IMPACT-EMAP 2014 will not be successful as this.

One week before the IMPACT-EMAP 2014, on October 15, I went to KINTEX in Ilsan, Korea, to attend and present at the ISMP-IAAC 2014 (The 13th International Symposium on Microelectronics and Packaging & IMAPS All Asia Conference 2014). On April 24, 2014, I had also made a presentation at the “Taiwan Session” of the ICEP 2014 (International Conference on Electronics Packaging 2014) in Toyama, Japan.

In this IMPACT-EMAP 2014, we not only had the “ICEP Japan Session,” organized and presented by ICEP; but also, for the first time, we added the “Meet Korea Session” this year, organized and presented by KEMPS (Korean Microelectronics and Packaging Society).

Although hosting and organizing international events like ISMP, ICEP and IMPACT, needs a lot efforts and supports. But through the efforts and the active participations of these international events, are the best opportunities to share and learn more about the new knowledge and technology.

ICEP (International Conference on Electronics Packaging) held in Japan has been an event I attended the most in Asia since 1982. It comes from the IMC (International Microelectronics Conference) and is co-organized by JIEP (Japan Institute of Electronics Packaging), IEEE CPMT-Japan and IMAPS-Japan.

Since then, I tried to attend or present at every IMC or ICEP. I did present some works and results of my own research. But in return, I learned a lot more from the superior and remarkable presentations at the conferences. I not only enjoyed sitting in the conference, listen to the presentations of the up-to-dated technology and knowledge from the outstanding scholars and experts around the world. I also learned a lot from the plant-visiting programs and the social programs. Besides these professional rewards, I had the opportunity to watch and learn how to organize a world-class event and its programs. I learned from the technical presentations, the people, the activities and the programs. **“Learning by Sharing”** is the best lesson and experience I have learned. When we present our works, we learned through the comments, questions, and discussions. We also learned from the presentations of the others. There is even more can be learned during our idea-exchanging conversations in the coffee breaks and banquets.

To publish our work in a prestigious journal, such as the Journal of Japan Institute of Electronics Packaging, is similar to present it at a good conference. The conference and the journal are served as the platforms. The readers of the journal can learn from the published paper. The author(s), on the other hand, learned through the submitting and revising/reviewing processes, communications with the referees, and the idea exchange or comments receiving from the readers. He or she offered and shared his (her) research achievements with the readers, and learned something from them at the same time. It is my sole impression on the presentation at a good conference and the publication in a prestigious journal, we are all **“Learning by Sharing.”**